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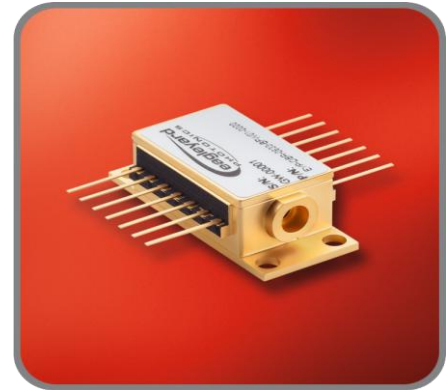
DISTRIBUTED BRAGG REFLECTOR LASER

GaAs Semiconductor Laser Diode with integrated grating structure



General Product Information

Product	Application
633 nm DBR Laser with hermetic Butterfly Housing	Replacement of HeNe-Lasers
Monitor Diode, Thermoelectric Cooler and Thermistor	Metrology
Collimated beam	
ROHS compliant	



Absolute Maximum Ratings

	Symbol	Unit	min	typ	max
Storage Temperature	T_S	°C	-40		85
Operational Temperature at Case	T_C	°C	-20		75
Operational Temperature at Laser Chip	T_{LD}	°C	0		25
Forward Current	I_F	mA			200
Reverse Voltage	V_R	V			2
Output Power	P_{opt}	mW			12
TEC Current	I_{TEC}	A			1.1
TEC Voltage	V_{TEC}	V			2.8

Stress in excess of the Absolute Maximum Ratings can cause permanent damage to the device.

Recommended Operational Conditions

	Symbol	Unit	min	typ	max
Operational Temperature at Case	T_C	°C	0		50
Operational Temperature at Laser Chip	T_{LD}	°C	10		15
Forward Current	I_F	mA		140	180
Output Power	P_{opt}	mW	2		10

Measurement Conditions / Comments

measured by integrated Thermistor

Characteristics at $T_{LD} = 15^\circ\text{C}$, $P_{opt} = 10\text{ mW}$

Parameter	Symbol	Unit	min	typ	max
Center Wavelength	λ_C	nm	632.0	633.0	634.0
Spectral Width (FWHM)	$\Delta\nu$	MHz		1	
Temperature Coefficient of Wavelength	$d\lambda / dT$	nm / K		0.045	
Current Coefficient of Wavelength	$d\lambda / dI$	nm / mA		0.001	

Measurement Conditions / Comments

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Characteristics at $T_{LD} = 15^{\circ}\text{C}$, $P_{opt} = 10\text{ mW}$

Parameter	Symbol	Unit	min	typ	max
Forward Current @ $P_{opt} = 10\text{ mW}$	I_F	mA			180
Threshold Current	I_{th}	mA			120
Slope Efficiency	η	W / A	0.15	0.4	
Sidemode Supression Ratio	SMSR	dB	30		
Degree of Polarization	DOP	%		90	
Divergence parallel (full angle, 1/e ²)	$\Theta_{ }$	°		0.1	
Divergence perpendicular (full angle, 1/e ²)	Θ_{\perp}	°		0.1	
Beam Width parallel (1/e ²)	$d_{ }$	mm		0.7	1.0
Beam Width perpendicular (1/e ²)	d_{\perp}	mm		0.6	1.0
Beam Propagation Factor	M^2		1	1.2	tbd

Measurement Conditions / Comments

E field perpendicular to base plate (see p. 4)
parallel to base plate (see p. 4)
perpendicular to base plate (see p. 4)
at window, parallel to base plate (see p. 4)
at window, perpendicular to base plate (see p. 4)

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Monitor Diode

Parameter	Symbol	Unit	min	typ	max
Monitor Detector Current	I_{mon}	μA	10		2000
Reverse Voltage Monitor Diode	$U_{R,MD}$	V	3		5

Measurement Conditions / Comments

$U_R = 5 V$

Thermoelectric Cooler

Parameter	Symbol	Unit	min	typ	max
Current	I_{TEC}	A		0.7	1.1
Voltage	U_{TEC}	V		1.7	2.8
Power Dissipation (total loss at case)	P_{loss}	W		0.4	0.5
Temperature Difference	ΔT	K			60

Measurement Conditions / Comments

$P_{opt} = 10 mW, \Delta T = 40 K$

$P_{opt} = 10 mW, \Delta T = 40 K$

$P_{opt} = 10 mW, \Delta T = 40 K$

$P_{opt} = 10 mW, \Delta T = |T_{case} - T_{LD}|$

Thermistor (Standard NTC Type)

Parameter	Symbol	Unit	min	typ	max
Resistance	R	$k\Omega$		10	
Beta Coefficient	β			3976	

Measurement Conditions / Comments

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Package Dimensions

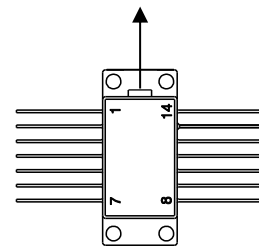
Parameter	Symbol	Unit	min	typ	max
Emission Plane	h_{EP}	mm		4.9	

Measurement Conditions / Comments

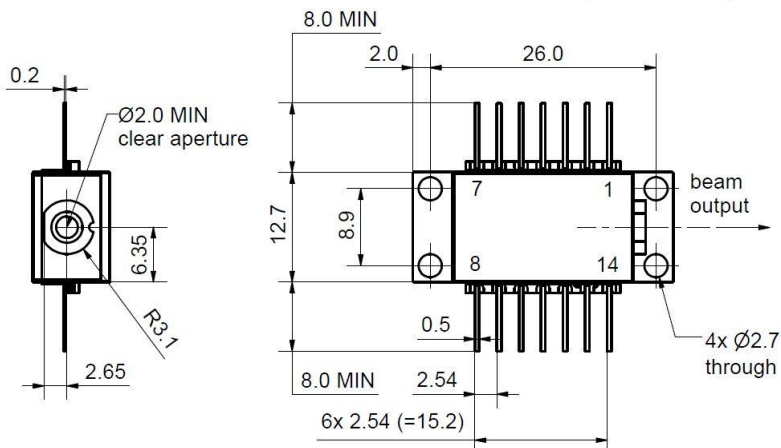
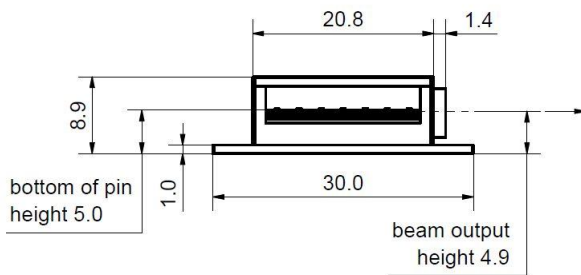
Package Pinout

1	Thermoelectric Cooler (+)	14	Thermoelectric Cooler (-)
2	Thermistor	13	Case
3	Photodiode (Anode)	12	not connected
4	Photodiode (Cathode)	11	Laser Diode (Cathode)
5	Thermistor	10	Laser Diode (Anode)
6	not connected	9	not connected
7	not connected	8	not connected

top view



Package Drawings



Polarization:

E field perpendicular to base plate

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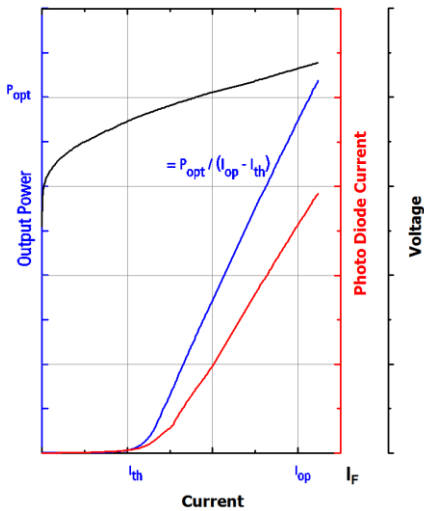
DISTRIBUTED FEEDBACK LASER

GaAs Semiconductor Laser Diode with integrated grating structure

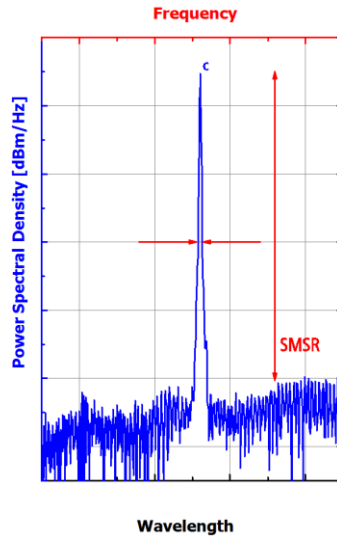


Typical Measurement Results

Output Power vs. Current



Spectra at Specified Optical Output Power



Pictures and the illustrative graphs (on the left hand side) provided in this specification are typical and must be specifically confirmed in writing by eagleyard Photonics before they become applicable to any particular order or contract.

Ordering Information:



800 Village Walk #316
Guilford, CT 06437
Ph: 203-401-8093

Email orders to: sales@xsoptix.com
Fax orders to: 800-878-7282

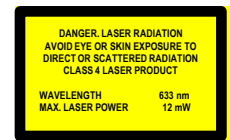
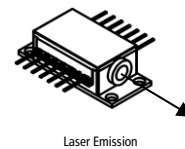
Unpacking, Installation and Laser Safety

Unpacking the laser diodes should only be done at electrostatic safe workstations (EPA). Though protection against electro static discharge (ESD) is implemented in the laser package, charges may occur at surfaces. Please store this product in its original package at a dry, clean place until final use. During device installation, ESD protection has to be maintained.

Operating at moderate temperatures on proper heat sinks will contribute to a long lifetime of the diode.

The laser emission from this diode is close to the invisible infrared region of the electromagnetic spectrum. Avoid direct and/or indirect exposure to the free running beam. Collimating the free running beam with optics as common in optical instruments will increase threat to the human eye.

Each laser diode will come with an individual test protocol verifying the parameters given in this document.



IEC 60825-1



Complies with 21 CFR 1040.10 and 1040.40